



Product Change Notification / LIAL-08IMMO486

Date:

15-Feb-2021

Product Category:

8-bit Microcontrollers, Capacitive Touch Sensors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4508 Initial Notice: Qualification of NSEB as a new assembly site for selected ATTINY20, ATTINY40, AT42QT2120, AT42QT1070, AT42QT1050 device families available in 20L VQFN (3x3x0.85mm) package.

Affected CPNs:

[LIAL-08IMMO486_Affected_CPN_02152021.pdf](#)

[LIAL-08IMMO486_Affected_CPN_02152021.csv](#)

Notification Text:

PCN Status:Initial notification

PCN Type:Manufacturing Change.

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of NSEB as a new assembly site for selected ATTINY20, ATTINY40, AT42QT2120, AT42QT1070, AT42QT1050 Atmel device families available in 20L VQFN (3x3x0.85mm) package.

Pre Change:

Assembled at ASKR using gold (Au) bond wire or palladium coated copper wire (PdCu) bond wire, EN-4900GC die attach material, C7025 lead frame material, NiPdAu lead frame lead plating, Spot plating lead frame DAP surface prep and without lead lock lead frame.

Post Change:

Assembled at NSEB using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, C194 lead

frame material, Matte Sn lead frame lead plating, Ag on lead only lead frame DAP surface prep and with lead lock lead frame.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	ASE Korea Inc (ASKR)		UTAC Thai Limited (UTL-1) LTD and (UTL-3) (NSEB)
Wire material	Au	PdCu	CuPdAu
Die attach material	EN-4900GC		8600
Molding compound material	G700		G700
Lead frame material	C7025		C194
Lead frame lead plating	NiPdAu		Matte Sn
Lead Frame DAP Surface Prep	Spot plating		Ag on lead only
Lead Frame Lead Lock	No		Yes
	See Pre and Post Change attachment for lead frame comparison		

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying NSEB as a new assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:September 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2021					-->	September 2021				
Workweek	06	07	08	09	10		36	37	38	39	40
Initial PCN Issue Date			X								
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change: Traceability code

Qualification Plan Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 15, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-08IMMO486_Qual Plan.pdf](#)

[PCN_LIAL-08IMMO486_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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